



# PRODUCT SPECIFICATION

## (產品規格書)

### Ordering information

2043-A 2X 40 G 00 D P U -H3.5

Series 2:Double No. of G: Gold 00:Gold D: SMD P : With Post U: Tube Plastic  
 Row Pin Per Row Plated Flash Type N : Without Package Height  
 Post

A1:FEB.02/2010.(新增)  
 A2:OCT.14/2015(額定電流)

PRODUCT NAME (產品名稱)	DOCUMENT No.: (文件編號)	Rev. (版本)	OUPIIN
P.C.B SOCKET  2.54mm SMD Type  (RoHS)	2043spec-A-H3.5	A2	(歐品)
	Approved (核準)	Checked (審核)	Prepared (製作)
	Q.A. Section Chief	Amy Chiu	OCT.14/2015



# PRODUCT SPECIFICATION OF OUPIIN

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## **1. SCOPE (範圍)**

This product specification defines the product performance and the test methods to ascertain the performance of the P.C.B SOCKET 2.54mm SMD Type, which is designed and manufactured by Oupiin Electronic Co.,Ltd.

(本產品規格書規定了由歐品電子有限公司生產的 P.C.B SOCKET 2.54mm SMD Type, 型連接器,產品的特性及測試方法.)

## **2. REFERENCE DOCUMENTS (參考文件)**

MIL-STD-1344A	Test method for electrical connector (電子連接器測試方法)
MIL-STD-202	Test method for electrical components (電子零件測試方法)
EIA364	Test method for electrical components (電子零件測試方法)

## **3. FEATURE & DIMENSIONS (特徵及尺寸)**

### **3.1. PRODUCT DIMENSION (產品尺寸)**

These connectors shall have the dimensions as shown in drawing.

(本產品的相關尺寸參考圖面.)

### **3.2. PCB/PANEL LAYOUT (印刷電路板佈局)**

The recommended PCB layout is shown in drawing.

(本產品適用的 PCB layout 參考圖面.)

### **3.3. BILL OF MATERIAL (材料清單)**

Harmful material control follow the requirement of RoHS. The bill of material and product number s described in drawing.

(有害物質控制符合RoHS指令要求.本產品使用的材料參考附件.)

### **3.4. MECHANICAL & ELECTRICAL CHARACTERISTIC (機械及電氣特性)**

The connector shall have the mechanical and electrical performance as described in drawing.

(本產品的機械及電氣特性見圖面：)

### **3.5. PACKAGING (包裝)**

Products shall be packaged according to requirements specified in purchase order for safe delivery, connector container and the packaging method are shown in package specification.

(產品可依客戶指定要求包裝，包裝材料與包裝方式參見產品包裝規範。)

### **3.6 RATING CURRENT AND RATING VOLTAGE 額定電流與額定電壓**

Rating current is 3.0A, rating voltage is 250V DC/AC RMS.

額定電流 3.0A，額定電壓 250V DC/AC RMS。

### **3.7 OPERATING TEMPERATURE 使用溫度**

Temperature range: -40°C~+105°C,.

溫度範圍：-40°C~+105°C。

## **4. ENVIRONMENTAL (環境要求)**

### **4.1. SOLDERABILITY (可焊性)**

Connectors meet solder ability to MIL-STD-202. Finish shall be free of contaminants.

(產品可焊性符合 MIL-STD-202 標準規定的相關要求，表面不得有污染物。)

### **4.2. RESISTANCE TO SOLDER HEAT (耐焊接熱)**

#### **INFRARED REFLOW (紅外線回流焊接)**

Three cycles. Each cycle consisting of three consecutive phased.

(三個週期，每個週期包括三個連續的階段完成；)

#### **1. Preheat (預熱)**

Increase in temperature not to exceed 4°C per second.

(溫度增加不超過 4°C /秒。)

#### **2. Soldering (焊接)**

Maximum allowable time above reflow temperature of 150~200°C is 90~120 seconds.

Maximum temperature in this interval is 260°C, not to exceed 5 seconds.

(回流焊溫度150~200°C時最長不超過90~120秒。最高溫度260°C時間不超過5秒。)

#### **3. Cool Down (冷卻)**

Cool down shall not exceed 6°C per second.

(冷卻速度不超過6°C/秒。)

#### **Note: (說明)**

Device temperature measurements are referenced from the top-center of the package outer surface.

(設備溫度量測時以從頂部中間位置測量為準。)

## **5. PERFORMANCE AND TEST DESCRIPTION**

### **(性能及測試)**

#### **5.1. REQUIREMENT (要求)**

Product is designed to meet electrical, mechanical, and environmental performance requirements specified in **Table I**.

(本產品設計符合附表一所述的機械，電氣及環境要求。)

#### **5.2. TEST CONDITION (測試條件)**

Unless otherwise specified, all tests shall be performed at ambient environmental conditions.

(除非特別注明，所有測試在室溫條件下完成；)

#### **5.3. SAMPLE SELECTION (樣品選擇)**

Test samples shall be selected at random from current production. No test samples shall be reused. Samples are pre-conditioned with 10cycles of durability. Each group shall be containing 5 test samples.

(測試樣品從現生產的產品中隨機抽取，所有測試過的樣品不得重複使用。樣品已預先插拔10次，每組測試有5個樣品；)

**Table I: Test Requirements and Procedures**
**(附錄一:測試要求)**

Items (項目)	Requirements (要求)	Test Methods (檢測方法)
1. Confirmation of Product (產品確認)	Product shall be conforming to the requirements of applicable product drawing. (產品必須滿足相關檔的規定)	Check the dimensions and functions per applicable product drawing in your eyes. (目視，尺寸及功能依產品圖面檢查)
2. Contact Resistance (接觸阻抗)	20 mΩ Max. (最大)	Subject mated contacts assembled in housing to closed circuit of 100 mA max. at open circuit voltage of 20 mV DC max. (所述固定在外殼裏的端子連結到一個封閉回路中 測試：電流 100 mA，電壓 20 mV DC max.)
3. Insulation Resistance (絕緣阻抗)	1000 MΩ Min. (最小)	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 302, Condition B (500 V DC±10%). (測試產品端子間以及端子與接地間的電阻，適用：MIL-STD-202,方法 302,條件 B )(500V DC±10%)
4. Dielectric Strength (耐電壓)	Connector must withstand test potential of 600 V AC for 1 minute.. (樣品必須承受測試電壓 600V AC)	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 301. (測試產品端子間以及端子與接地間的電壓，適用：MIL-STD-202，方法 301。)
5. Durability (Repeated Mating/Unmated) (耐久性)	Contact Resistance: 30 mΩ Max. after testing. (測試後接觸阻抗最大 30mΩ)	The sample should be mounted the tester and fully mated and unmated 100 cycles specified at the rate of 25mm/min (重復進行配合產品 100 次插拔.)
6. Connector Pin Mated / Un-mated Force (單 PIN 插入力/拔出力)	Insertion / Mated force : 4 N max. per contact Withdrawal / Unmated force : 0.3 N min. per contact 插入力: 4 N 最大/PIN 拔出力: 0.3 N 最小/PIN	Measure force necessary to unmated between the counterparts connectors.. (軸向力以 25±3mm/分的速度從塑膠本體對插後拔出)



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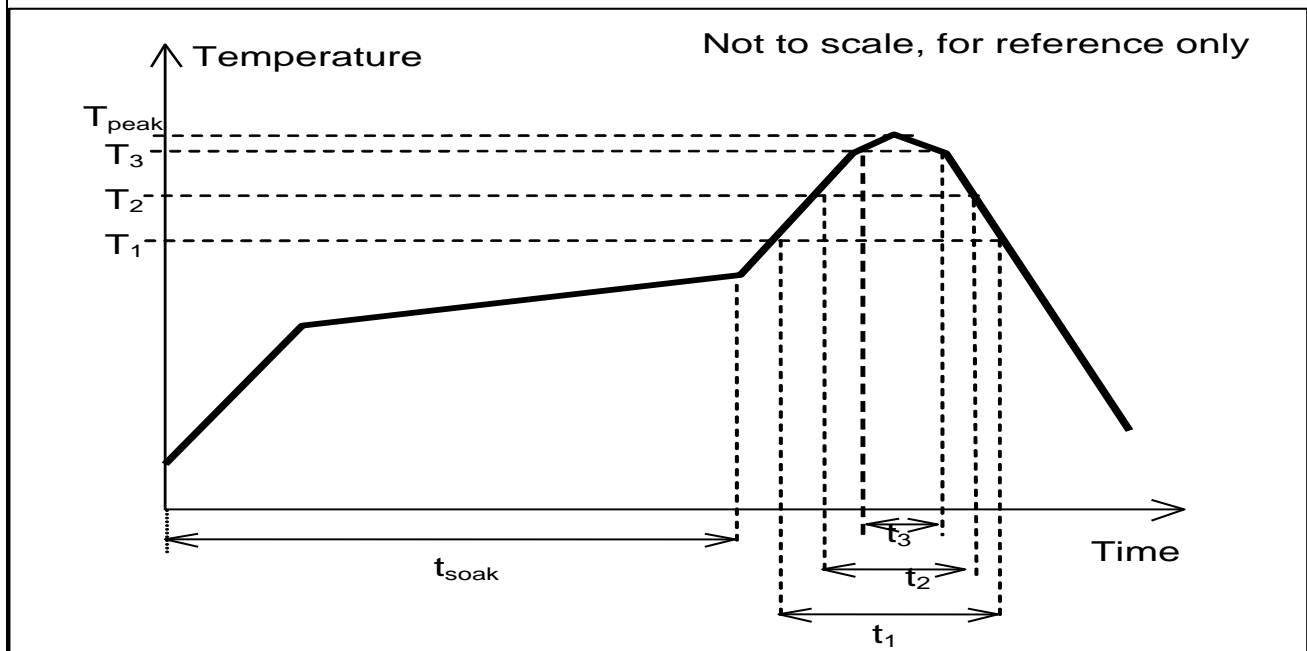
7. Thermal shock (熱衝擊)	After testing, no damage, Contact Resistance 30 mΩ max.. (測試後,產品無損壞, 接觸阻抗: 30 mΩ 最大)	Temperature range from -40°C to +105°C .Start from -40°C, after 30 min. change to +105°C; change time is no more than 30 seconds. Total 5 cycles. MIL-STD-202, Method 107D, condition A. (溫度變化範圍: -40°C~ +105°C; 從 -40°C 開始, 30 分鐘後換到+105°C; 轉換時間不超過 30 秒; 共 5 個循環.適用: MIL-STD-202, 方法 107D, 條件 A.)
8. Humidity (恆溫恆濕)	After testing, no damage, Contact Resistance 30 mΩ max.. Dielectric Strength should be OK, Insulation Resistance should be 500 MΩ min. (測試後,產品無損壞, 接觸阻抗: 30 mΩ 最大; 耐電壓測試 OK, 絕緣阻抗 500MΩ 最小;)	Temperature :40±2°C 96 hours. (溫度: 40±2°C 96 小時) Relative Humidity : 90-95%; (相對濕度 : 90-95%; ) Duration :96 Hours. MIL-STD-202, Method 108, (時間: 96 小時; MIL-STD-202, 方法 108。)
9. Salt Spray (鹽霧)	After testing, no damage, Contact Resistance 30 mΩ max.. (測試後,產品無損壞, 接觸阻抗: 30 mΩ 最大)	5±1% salt concentration 16±1 hours 35±2°C MIL-STD-202, Method 101 Condition B. (鹽水濃度 (重量比) 5±1%, 時間 8 小時, 溫度 35±2°C; MIL-STD-202, 方法 101 條件 B.)
10. Solderability Test-I719 (可焊性測試)	Soldering time: 3 to 5 Seconds (焊接時間: 3~5 秒) Peak Temperature: 245±5°C. (最高溫度: 245±5°C.)	After exposure, the contact solder tails shall have a minimum of 95% solder coverage. The covered area must not show any evidence of voids or pinholes. The test shall be in ccordance with EIA-364-71B, The following details shall apply

**Table II: Reflow soldering profile**

(附錄二:回流焊接曲線圖)

**Pb-free reflow profile requirements: (無鉛回流焊接曲線)**

Parameter (參數)	Reference (參考)	Specification (規格)
Average Temperature Gradient in Preheating (平均預熱溫度)		2.5°C/s
Soak Time 25~150°C	$T_{soak}$	60 Seconds (max)
Time Above 150~200°C	$t_1$	120 Seconds (max)
Time Above 200~230°C	$t_2$	60 Seconds (max)
Time Above 230~245°C	$t_3$	15~10 Seconds (max)
Peak temperature in reflow (回流焊接中最高溫度)	$T_{peak}$	260°C (-5/+0°C)
Temperature Gradient in Cooling (冷卻時溫度幅度)		Max -5°C/s



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile largely dependent on the reflow equipment.

(這個曲線圖是評估原器件焊接抗熱的基本要求. 應用在對流焊接中的熱傳遞方式是熱氣對流. 達到特定曲線圖的實際溫度主要依賴於回流焊接設備.)



Material Housing : 017-LCP (Black)

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## 1. General physical properties of VECTRA® E130i

Table 1-1 General properties (ISO)

Item	Unit	Testing Method	High Heat Resistance/High Flow
			E130i
			Glass Fiber, Standard
Density	g/cm <sup>3</sup>	ISO 1183	1.61
Tensile strength*	MPa	ASTM D638	175
Tensile elongation*	%	ASTM D638	2
Flexural strength	MPa	ISO 178	220
Flexural modulus	MPa	ISO 178	15000
Flexural strain	%	ISO 178	2.3
Charpy impact strength(notched)	kJ/m <sup>2</sup>	ISO 179/1eA	35
Temperature of deflection under load(1.8MPa)	°C	ISO 75-1,2	280
Mold Shrinkage(80×1mmt, Flow direction, Injection pressure59MPa)	%		0.02
Mold Shrinkage(80×1mmt, Transverse direction, Injection pressure59MPa)	%		0.54
Mold Shrinkage(80×1mmt, Flow direction, Injection pressure79MPa)	%		-
Mold Shrinkage(80×1mmt, Transverse direction, Injection pressure79MPa)	%		-
Volume resistivity	Ohm·cm	IEC 60093	1.0×10 <sup>16</sup>
Surface resistivity	Ohm	IEC 60093	1.0×10 <sup>16</sup>
Dielectric constant(1kHz)		IEC 60250	4.3
Dielectric constant(1MHz)		IEC 60250	3.8
Dielectric constant(10GHz)			3.6
Dielectric dissipation factor(1kHz)		IEC 60250	0.017
Dielectric dissipation factor(1MHz)		IEC 60250	0.032
Dielectric dissipation factor(10GHz)			0.007
Dielectric breakdown strength(Thickness 1mm)	kV/mm	IEC 60243-1	44
Dielectric breakdown strength(Thickness 3mm)	kV/mm	IEC 60243-1	24
Tracking resistance (CTI)	CTI	IEC 60112	125
Arc resistance	s		130
Flammability		UL94	V-0

All figures in the table are the typical values of the material and not the minimum values of the material specifications.

\*1)For qualified values of UL (Underwriters Laboratories Inc.) refer to the yellow card (File No.E106764 ) issued by UL.

\*2)This grade comes under Item 16 of Annex 1 of the Export Trade Control Order on the basis of the Foreign Exchange and Foreign Trade Law of Japan.



# PRODUCT SPECIFICATION OF OUPIIN

## Material Housing :UL

QMFZ2 Component - Plastics

Friday, August 10, 2001

E106764

### POLYPLASTICS CO LTD

VECTRA DIV, KASUMIGASEKI BLDG, 6TH FL 2-5 KASUMIGASEKI 3-CHOME CHIYODA-KU TOKYO 100-6006 JAPAN

Material Designation: **E130i(d)(e)**

Product Description: Liquid Crystal Polymer (LCP), thermotropic aromatic polyester, designated "Vectra" furnished as pellets.

Color	Min. Thick. (mm)	Flame Class	HWI	HAI	RTI Elec	RTI Imp	RTI Str	IEC GWIT	IEC GWFI
ALL	0.75	V-0	2	4	240	220	240	-	-
	1.5	V-0	1	4	240	220	240	-	-
	3.0	V-0	0	4	240	220	240	-	-
<b>CTI: 4</b>			<b>HVTR: 0</b>		<b>D495: 5</b>		<b>IEC BP: -</b>		

(d) Virgin and regrind up to 50% by weight incl. have the same basic material characteristics: for colors NC and BK.

(e) In addition, regrind at 26 to 50% have the same basic characteristics at a minimum of 1.5mm except RTI's for the Mechanical w/Impact property is 180C.

Report Date: 08/19/1992

Underwriters Laboratories Inc®

593273003

UL94 small-scale test data does not pertain to building materials, furnishings and related contents. UL 94 small-scale test data is intended solely for determining the flammability of plastic materials used in components and parts of end-product devices and appliances, where the acceptability of the combination is determined by UL.

Material Contact : Copper Alloy (Phosphor Bronze)

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**REPORT OF MATERIAL TEST**  
**材料測試報告**

ISO 9001  
ISO/TS 16949  
IECQ QC080000  
ISO 14001  
OHSAS 18001 & TOSHMS

No.: 372166

DATE: JUL.30,2014

Customer 顧客名稱 : 歐品電子有限公司  
Commodity 商品名稱 : C 5191 R PHOSPHOR BRONZE STRIP ( H )  
Applied Standard 引用標準 : JIS H 3110 Phosphor bronze sheets, plates and strips

Manufacture No.	銅帶卷號	36C063C	
(Specification)	產品規格	Standard	
Thickness (mm)	產品厚度		0.250
Width (mm)	產品寬度		15.000
Length (mm)	產品長度		
(Chemical Analysis Test)	化性測試		
P(%)	磷	0.030 - 0.350	0.118
Sn(%)	錫	5.500 - 7.000	5.807
Cu+Sn+P(%)	銅錫磷	min. 99.500	99.958
(Mechanical & Physical Test)	物性測試		
Thickness Test (mm)	厚度測試	-0.010 +0.010	0.249
Width Test (mm)	寬度測試	-0.10 +0.00	GOOD
Tensile Strength (kgf/mm <sup>2</sup> )	抗拉強度	58.00 - 65.00	61.09
Elongation (%)	伸長率	min. 10.00	25.08
Hardness Test (Hv)	硬度	180.0 - 210.0	192.0 - 194.0
Grain Size (mm)	結晶粒徑	-	-
Electric Conductivity (%)	導電率	-	16.40
(Other Information)	其他資訊		
Delivery No.	出貨單號	37A110	
Customer Purchase Order	採購單號	PO.B02A14061311	



MINCHALI METAL INDUSTRY CO., LTD.  
名佳利金屬工業股份有限公司  
11, Pei Yuan Road, Chung Li City, Taiwan, R.O.C.  
Tel : (03)4526141-5 (03)4526017-9  
Fax : (03)4529112 (03)4629625

QA Supervisor: 周建偉

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